

AM2520SURCK09

HYPER RED

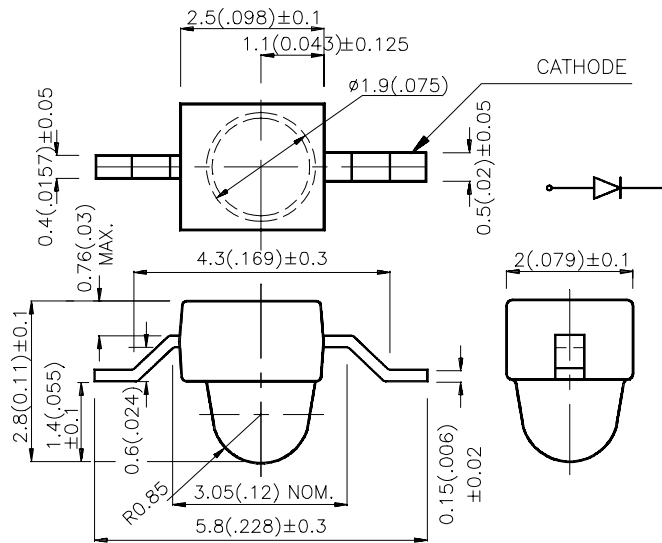
Features

- SUBMINIATURE PACKAGE.
- WIDE VIEWING ANGLE.
- Z-BEND LEAD.
- LONG LIFE - SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE : 1000PCS / REEL.

Description

The Hyper Red source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
AM2520SURCK09	HYPHER RED (InGaAlP)	WATER CLEAR	200	700	20°

Note:

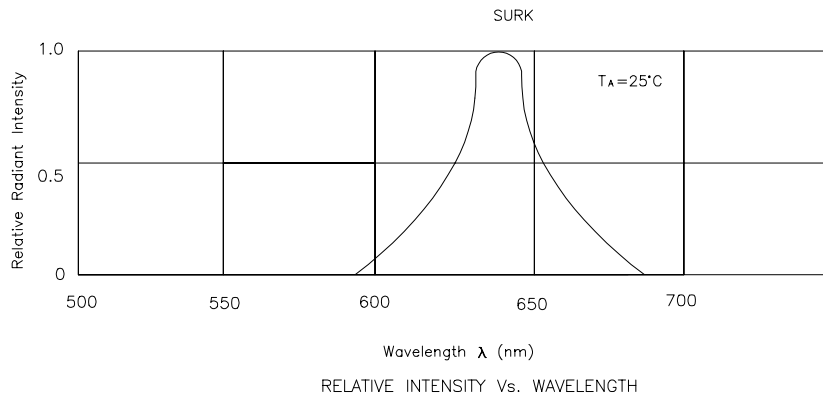
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25°C

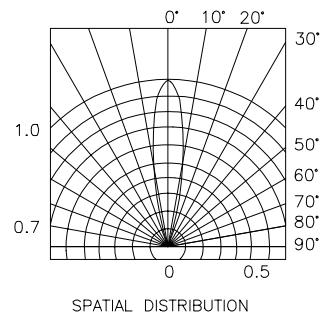
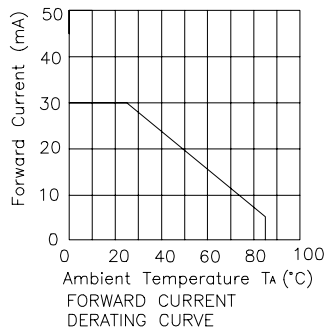
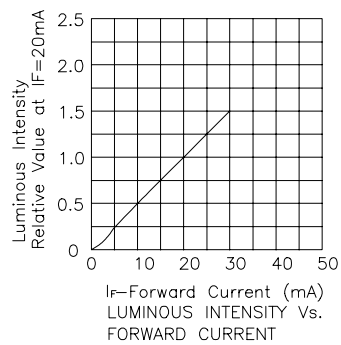
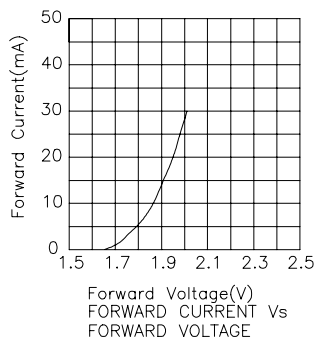
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Hyper Red	640		nm	IF=20mA
λ _D	Dominate Wavelength	Hyper Red	630		nm	IF=20mA
Δλ _{1/2}	Spectral Line Halfwidth	Hyper Red	28		nm	IF=20mA
C	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
V _F	Forward Voltage	Hyper Red	1.95	2.5	V	IF=20mA
I _R	Reverse Current	Hyper Red		10	uA	VR = 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	Hyper Red	Units
Power dissipation	170	mW
DC Forward Current	30	mA
Peak Forward Current [1]	185	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

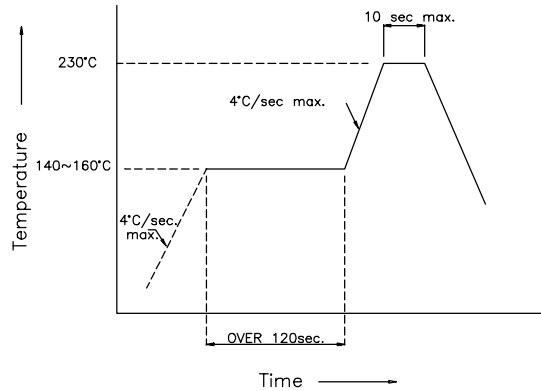


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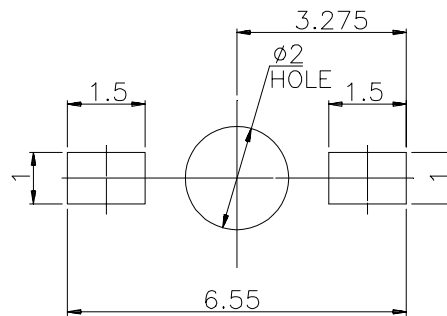


AM2520SURCK09 SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

